Low Concentration Zirconia Oxygen Analyzer based on our long and field-proven experience

The OX400 is a highly accurate and reliable low concentration zirconia oxygen analyzer that is capable of measuring a wide range of concentrations, from 0-10 ppm up to 0-100 vol% O₂. This is the latest oxygen analyzer from Yokogawa, and its development was based on the company's long experience and strong track record with this technology. A proprietary new thin-film deposition technology was used in the zirconia sensor that creates a molecular bond between the zirconia element and the platinum layer. This prevents separation, enables a reduction in sensor size and ensures a high-speed response and long life.

Features

Long life and high-speed response
- Thanks to the use of Yokogawa's proprietary new thin-film deposition technology, the sensor has three times the lifespan of those used in our earlier products.
- A cylindrical sensor design facilitates the replacement of measurement gases, thereby helping to assure a high-speed response.

Built-in functions and a variety of self-diagnosis functions
- Comes with multi-selector, free-range, and pump on/off functions
- A variety of self-diagnosis functions are provided that detect malfunctions such as heater temperature error, temperature sensor burnout, and sensor resistance value error.

High performance and high reliability
- Superior repeatability and linearity even at low oxygen concentrations
- Either pump or aspirator sampling can be selected, depending on the application.
- Enhance safety, various standards. (CE, RCM, cCSAus)

Superior maintainability
- The sensor can be replaced on-site.
- Compact and lightweight for easy installation.
Applications

- Oxygen concentration control in semiconductor-related diffusion and drying furnaces and in LCD manufacturing processes
- Oxygen concentration control in solder pot flow and reflow ovens, and glove boxes used in electronics manufacturing, and in gas production processes
- Oxygen concentration measurements to prevent dust explosions during powder transfer

Semiconductor, Liquid Crystal (FPD) Process

Reflow Furnace

For details, refer to General Specification, GS11M10B01-01E